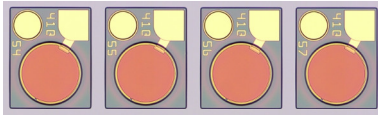
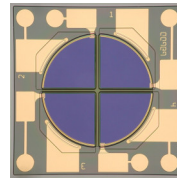


Monitoring & Sensing Solutions



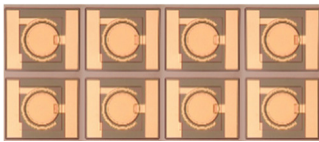
Multi-Channel Top Illuminated Photodiode Array

- Scalable multi-channel photodiode array
- Channel pitch of 250 μm
- Laser monitoring and Sensing applications
- Easy coupling into large optical aperture of 150 μm
- Wide wavelength range from 980 nm to 1620 nm



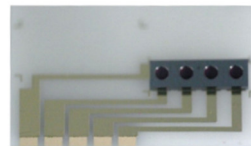
Four Quadrant Photodiode

- Photodiode segmented into four individual quadrants
- Position sensing and beam profiling
- Large active area
- Small quadrant separation
- Dedicated anode and cathode pads
- High responsivity at 1550 nm
- Also available in TO-can package



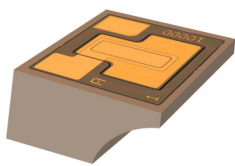
2x4 Bottom Illuminated 2D Photodiode Array

- Scalable multi-channel photodiode array
- Channel pitch of 300 μm in x- and 250 μm in y-direction
- LIDAR and Sensing applications
- Easy coupling into large backside aperture
- Pad layout optimized for flip-chip soldering
- Customized submount layouts



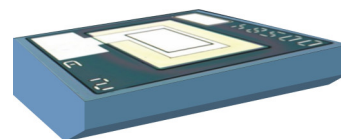
4 x 2.5G Photodiode Array on Carrier

- 4 channel photodiode array flip-chip soldered onto a ceramic carrier with wrap-around metallization
- Scalable multi-channel photodiode array
- Channel pitch of 250 μm
- Laser monitoring
- Easy coupling into large backside aperture
- Customized submount layouts



Side Illuminated Monitor Photodiode

- Cost effective, small die size
- No need for large and expensive "wrap-around" submount
- Laser back facet monitoring
- High coupling efficiency through curved side facet
- Wide wavelength range from 1260 to 1620 nm
- Topside wire-bondable pads for both anode and cathode



Side Illuminated Low Entry Monitor Photodiode

- No need for large and expensive "wrap-around" submount
- Back facet monitoring of edge emitting lasers mounted p-side down
- Incoming light refracted through angled side facet
- Topside wire-bondable anode pad
- Bottom side cathode pad can be soldered or glued with conductive epoxy

PRODUCT OVERVIEW